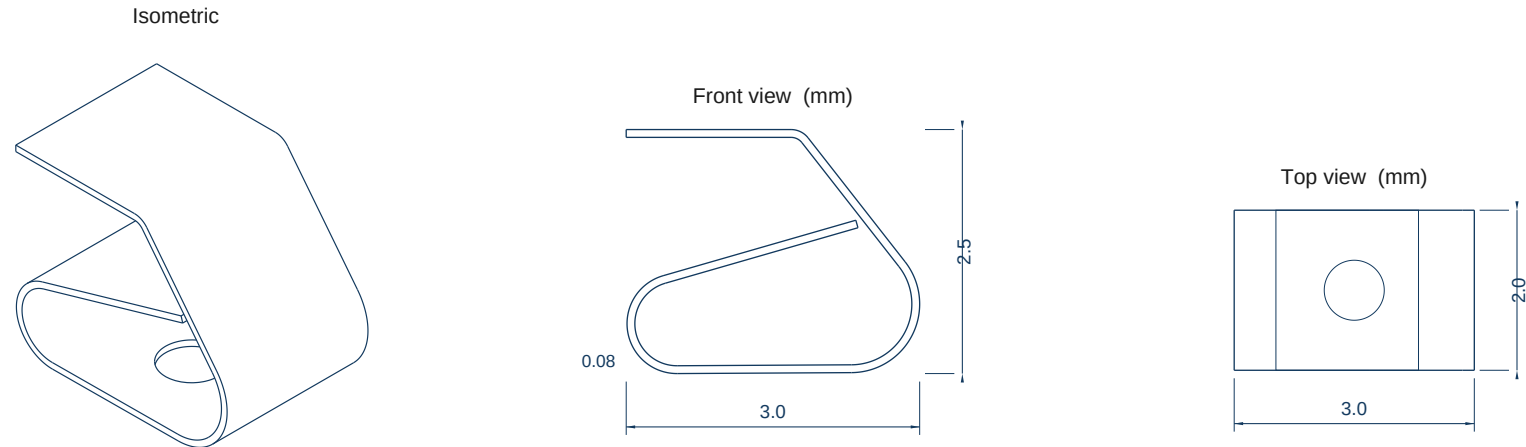




Type C-12 BC12-20030025

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.08 mm
Width	2.0 mm +/- 0.2
Length	3.0 mm +/- 0.2
Height	2.5 mm +/- 0.2
Form	top plate, sloping web, base plate, curled return tongue
Top bend	R0.181 CL, 52 deg
Curls	R0.661 CL, 128 deg (right) / R0.470 CL, 164 deg (left)
Sloping web	1.61 mm at 52 deg to the plates
Return tongue	2.05 mm
Base hole	dia 0.75 mm, centred
Developed length	10.11 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	1.583 mm ³ 13.2 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	BC12-20030025G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 3.0x2.0x2.5mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-c-12.html
File format	STEP AP214